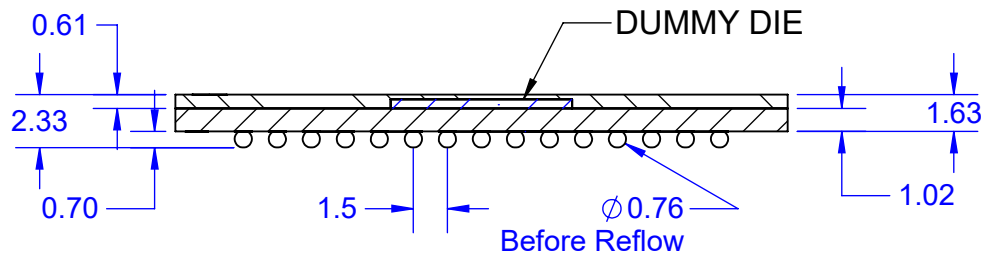
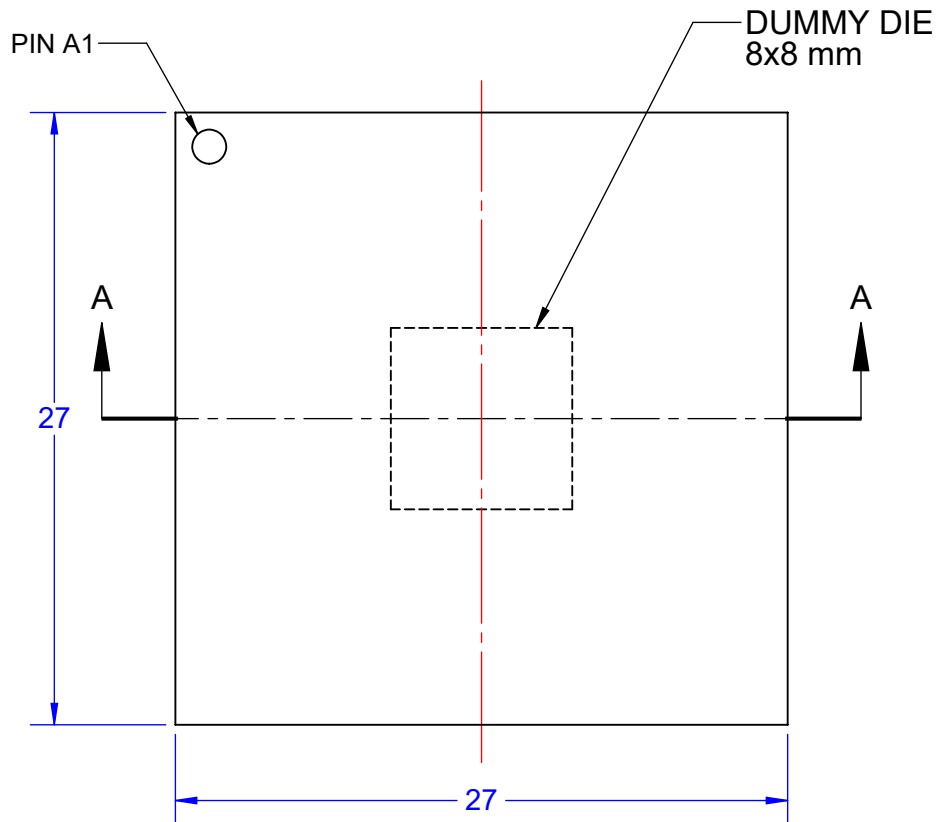
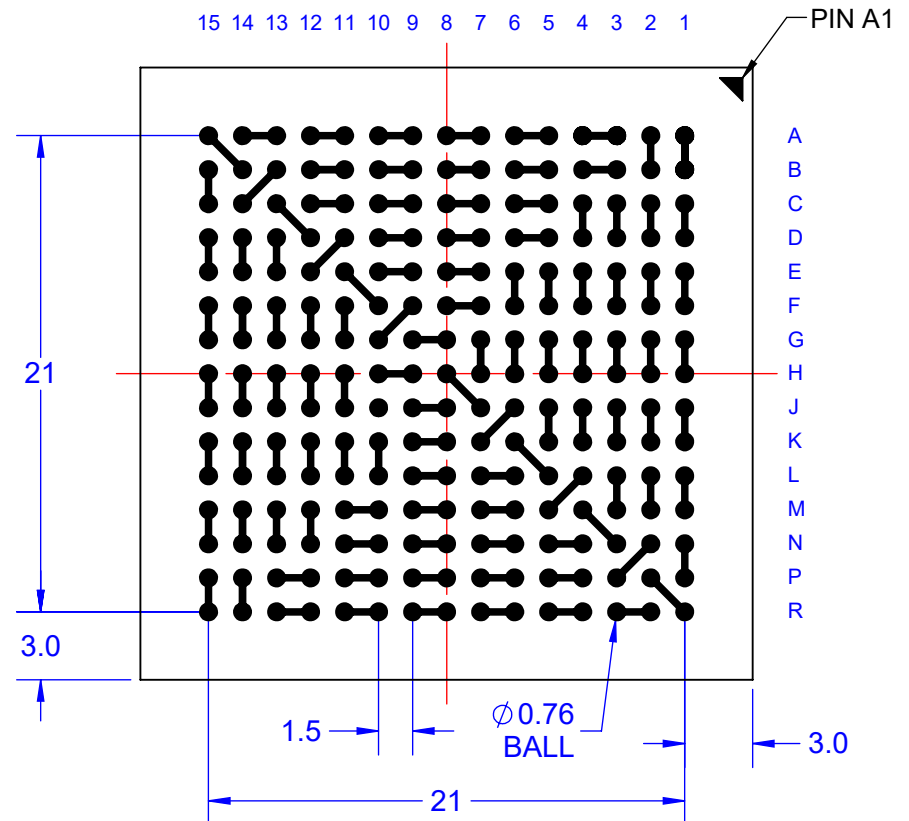


TOP VIEW



SECTION A-A
SCALE 3 : 1

BALL VIEW




Notes: (Unless Otherwise Specified).

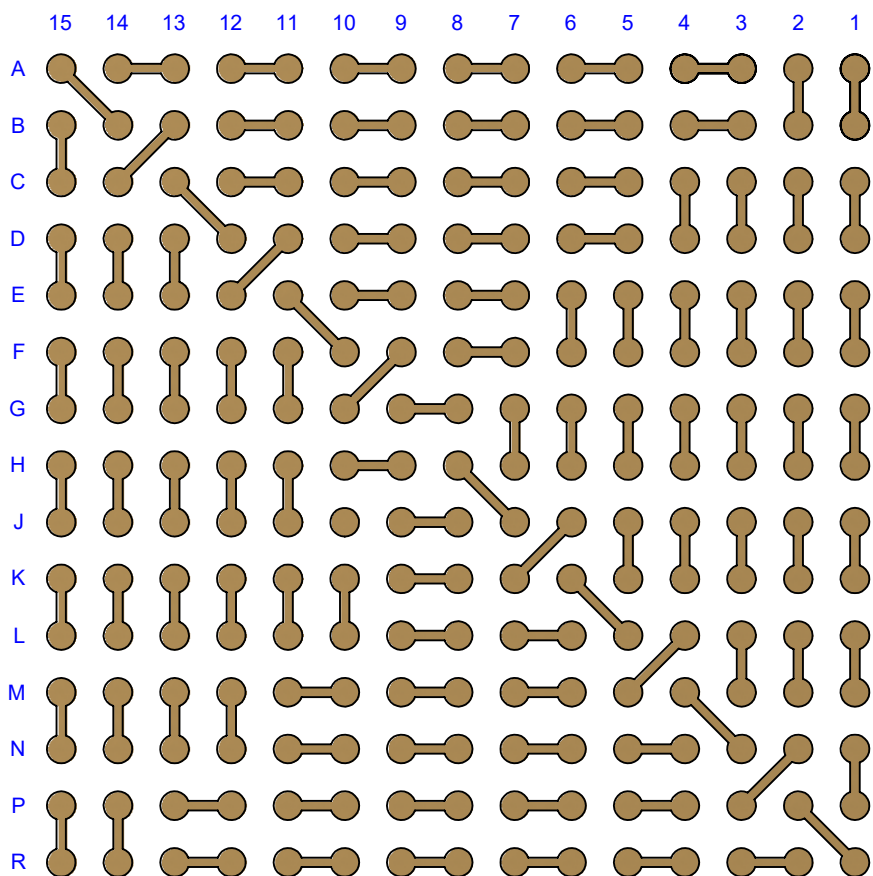
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.76 mm (30 MIL).
- 4) SOLDER MASK DEFINED PAD SRO 0.61 mm (24 MIL).
- 5) PAD Cu DIAMETER: 0.76 mm (30 MIL).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATIVE FR4)
- 7) DUMMY DIE IS OPTIONAL.
- 8) BALL PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

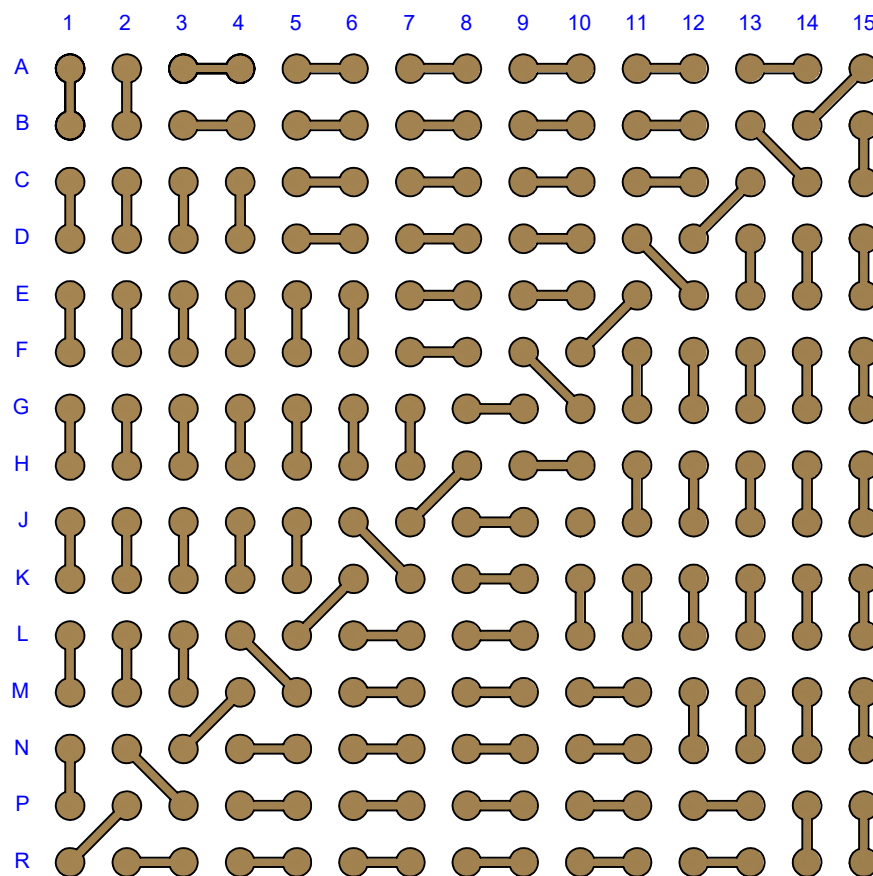
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA225T1.5C-DC15D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA225T1.5-DC15D	Sn63/Pb37	Sn63	NO	YES

APPROVALS		DATE				
DRAWN	T.Au	11/6/2021				
ENG	M. Hart	11/6/2021	TITLE		BGA225T1.5C-DC15D DAISY CHAIN	
MFG			SCALE		SIZE	DRAWING NO.
QA			3:1		A	521593
CUST						REV A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 4

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



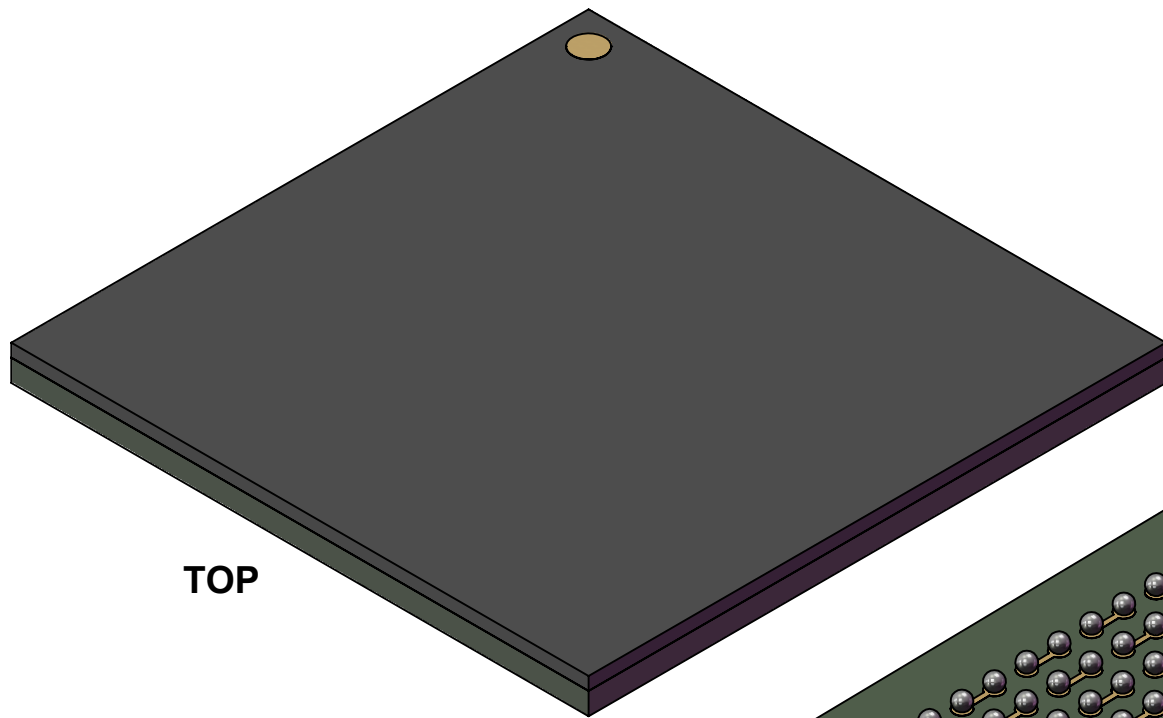
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.76 mm (30 MIL).
- 3) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.61 mm (24 MIL).
- 4) PCB TRACING LINE WIDTH 0.25 mm (10 MIL).

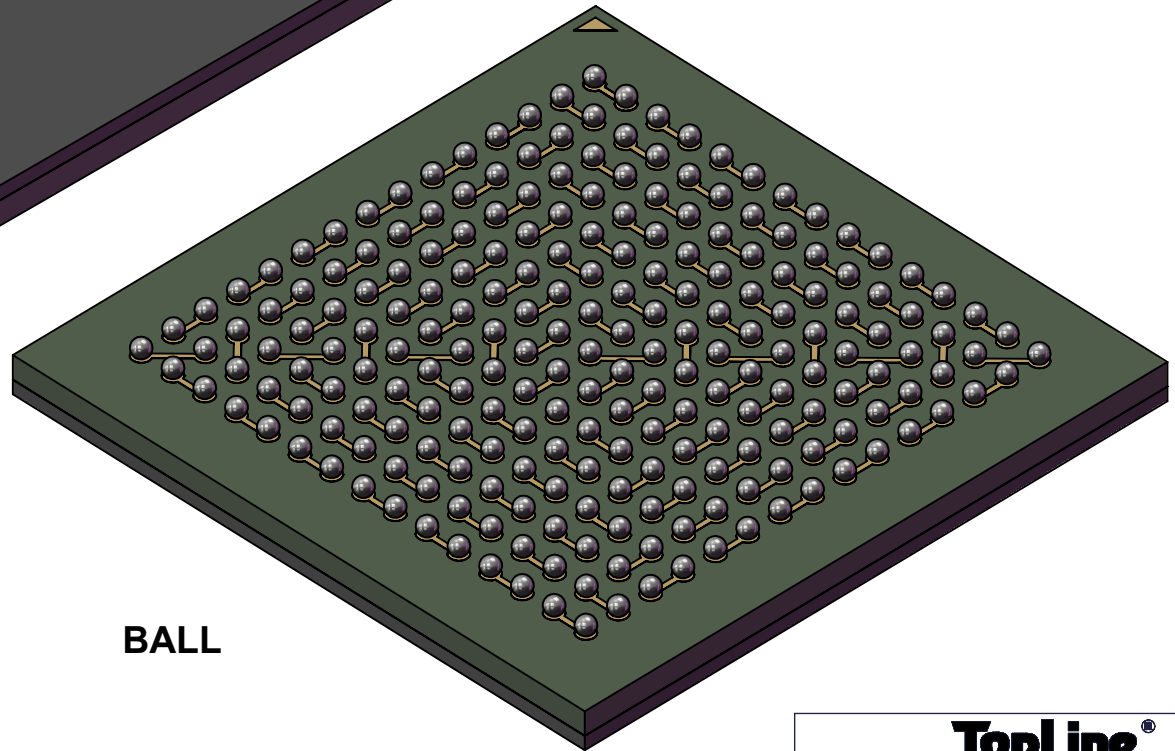
TopLine®

TITLE				BGA225T1.5C-DC15D DAISY CHAIN			
SCALE	SIZE	DRAWING NO.		REV			
5:1	A	521593		A			
DO NOT SCALE DRAWING						SHEET 2 OF 4	

**MODEL
BGA WITH BALL**



TOP



BALL

TopLine®

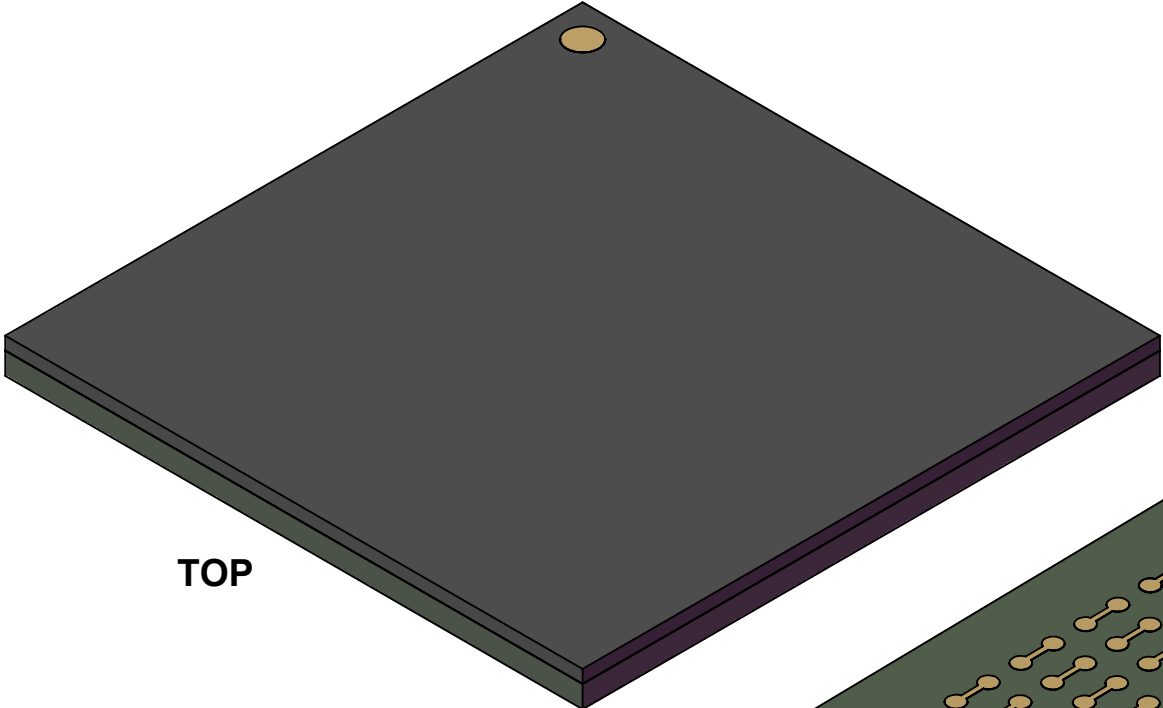
TITLE BGA225T1.5C-DC15D
DAISY CHAIN

SCALE 4:1	SIZE A	DRAWING NO. 521593	REV A
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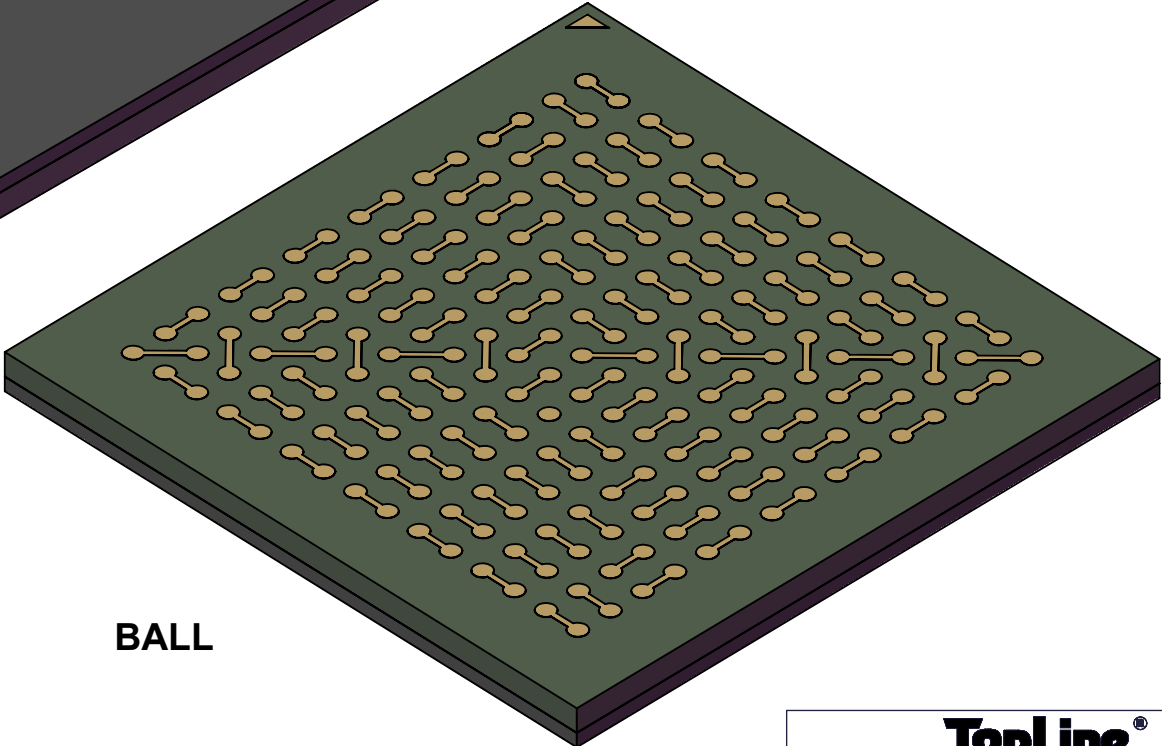
DO NOT SCALE DRAWING

SHEET 3 OF 4

**MODEL
LGA WITHOUT BALL**



TOP



BALL



TITLE LGA225T1.5G-DC15D
DAISY CHAIN

SCALE 4:1	SIZE A	DRAWING NO. 521593	REV A
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